

ABSTRACT OF THE DISCLOSURE

An inspection unit is provided in a substrate processing apparatus performing resist coating processing and development processing on a substrate. In the inspection unit, a film thickness measuring device, a line width measuring device, an overlay measuring device and a macro defect inspection device are successively stacked and arranged from below. The inspection unit is provided on an intermediate portion of a substrate transport path formed in the substrate processing apparatus. The substrate processed in the substrate processing apparatus is selectively introduced into each inspection part. Therefore, the apparatus can properly inspect the substrate at need while suppressing reduction of the throughput. Thus provided are a substrate processing apparatus and a substrate inspection method capable of properly inspecting a substrate while suppressing reduction of the throughput.

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